APR 1-5 2002

503.35443VX1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s):

NAGAI, et al.

Serial No.:

09/493,210

Filed:

January 28, 2000

For:

CIRCUIT TAPE HAVING ADHESIVE FILM,

SEMICONDUCTOR DEVICE, AND A METHOD FOR

MANUFACTURING THE SAME

Group:

2815

Examiner:

L. Cruz

AMENDMENT

Assistant Commissioner for Patents Washington, D.C. 20231

April 15, 2002

Sir:

In response to the Office Action mailed January 14, 2002, please amend the above-identified application as follows:

IN THE SPECIFICATION

Please add the following new paragraph on page 8, after line 1, as follows:

-- Fig. 9 shows a semiconductor device with a three layer structure for the

adhesive layer. Shown is earlayer (e.g., porous supporting layer) 10 with